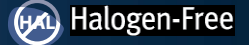


EPC2059 – Enhancement Mode Power Transistor

 $V_{DS}, 170\text{ V}$
 $R_{DS(on)}, 9\text{ m}\Omega$
 $I_D, 24\text{ A}$


Gallium Nitride's exceptionally high electron mobility and low temperature coefficient allows very low $R_{DS(on)}$, while its lateral device structure and majority carrier diode provide exceptionally low Q_G and zero Q_{RR} . The end result is a device that can handle tasks where very high switching frequency, and low on-time are beneficial as well as those where on-state losses dominate.

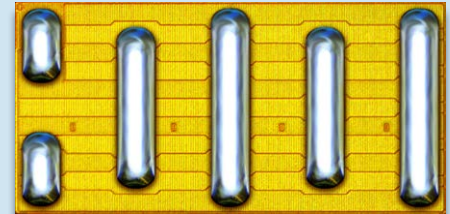
Maximum Ratings

PARAMETER		VALUE	UNIT
V_{DS}	Drain-to-Source Voltage (Continuous)	170	V
I_D	Continuous ($T_A = 25^\circ\text{C}$)	24	A
	Pulsed (25°C , $T_{PULSE} = 300\text{ }\mu\text{s}$)	102	
V_{GS}	Gate-to-Source Voltage	6	V
	Gate-to-Source Voltage	-4	
T_J	Operating Temperature	-40 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-40 to 150	

Thermal Characteristics

PARAMETER		TYP	UNIT
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.9	$^\circ\text{C}/\text{W}$
$R_{\theta JB}$	Thermal Resistance, Junction-to-Board	3	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	63	

Note 1: $R_{\theta JA}$ is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board. See https://epc-co.com/epc/documents/product-training/Appnote_Thermal_Performance_of_eGaN_FETs.pdf for details.



EPC2059 eGaN® FETs are supplied only in passivated die form with solder bars.
Die Size: 2.8 mm x 1.4 mm

Applications

- DC-DC Converters
- Sync rectification for AC/DC & DC-DC
- USB-C PD Quick Chargers & Adaptors
- BLDC Motor Drives
- Lidar
- Class-D Audio

Benefits

- Ultra High Efficiency
- No Reverse Recovery
- Ultra Low Q_G
- Small Footprint



Static Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-to-Source Voltage	$V_{GS} = 0\text{ V}$, $I_D = 0.15\text{ mA}$	170			V
I_{DSS}	Drain-Source Leakage	$V_{GS} = 0\text{ V}$, $V_{DS} = 136\text{ V}$		0.03	0.1	mA
I_{GSS}	Gate-to-Source Forward Leakage	$V_{GS} = 5\text{ V}$		0.01	2.4	
	Gate-to-Source Forward Leakage [#]	$V_{GS} = 5\text{ V}$, $T_J = 125^\circ\text{C}$		0.13	5.5	
	Gate-to-Source Reverse Leakage	$V_{GS} = -4\text{ V}$		0.03	0.2	
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 3\text{ mA}$	0.7	1	2.5	V
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS} = 5\text{ V}$, $I_D = 10\text{ A}$		6.8	9	m Ω
V_{SD}	Source-Drain Forward Voltage	$I_S = 0.5\text{ A}$, $V_{GS} = 0\text{ V}$		1.6		V

[#] Defined by design. Not subject to production test.

Dynamic Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
C_{ISS}	Input Capacitance [#]	$V_{DS} = 85\text{ V}, V_{GS} = 0\text{ V}$		633	836	pF
C_{RSS}	Reverse Transfer Capacitance			1.6		
C_{OSS}	Output Capacitance [#]			267	401	
$C_{OSS(ER)}$	Effective Output Capacitance, Energy Related (Note 2)	$V_{DS} = 0\text{ to }85\text{ V}, V_{GS} = 0\text{ V}$		332		
$C_{OSS(TR)}$	Effective Output Capacitance, Time Related (Note 3)			414		
R_G	Gate Resistance			0.5		Ω
Q_G	Total Gate Charge [#]	$V_{DS} = 85\text{ V}, V_{GS} = 5\text{ V}, I_D = 10\text{ A}$		5.7	7.4	nC
Q_{GS}	Gate-to-Source Charge	$V_{DS} = 85\text{ V}, I_D = 10\text{ A}$		1.3		
Q_{GD}	Gate-to-Drain Charge			0.9		
$Q_{G(TH)}$	Gate Charge at Threshold			1.0		
Q_{OSS}	Output Charge [#]	$V_{DS} = 85\text{ V}, V_{GS} = 0\text{ V}$		35	53	
Q_{RR}	Source-Drain Recovery Charge			0		

[#] Defined by design. Not subject to production test.

Note 2: $C_{OSS(ER)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 50% BV_{DSS} .

Note 3: $C_{OSS(TR)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 50% BV_{DSS} .

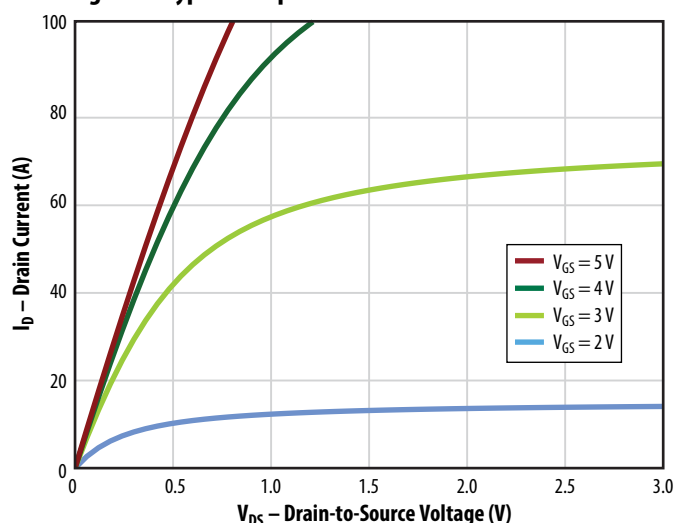
Figure 1: Typical Output Characteristics at 25°C 

Figure 2: Transfer Characteristics

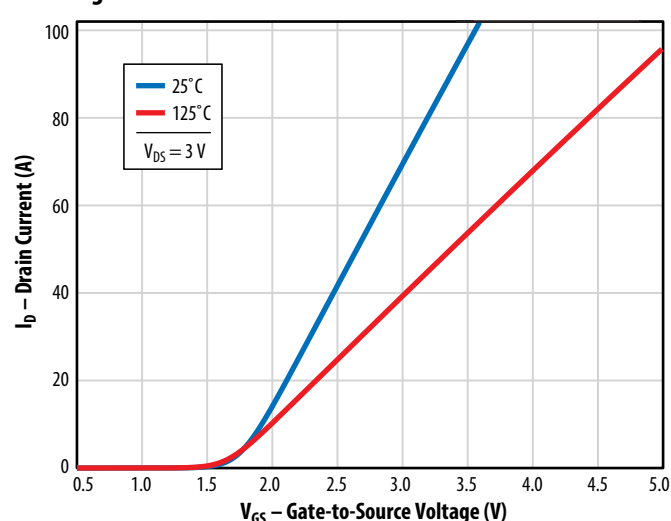
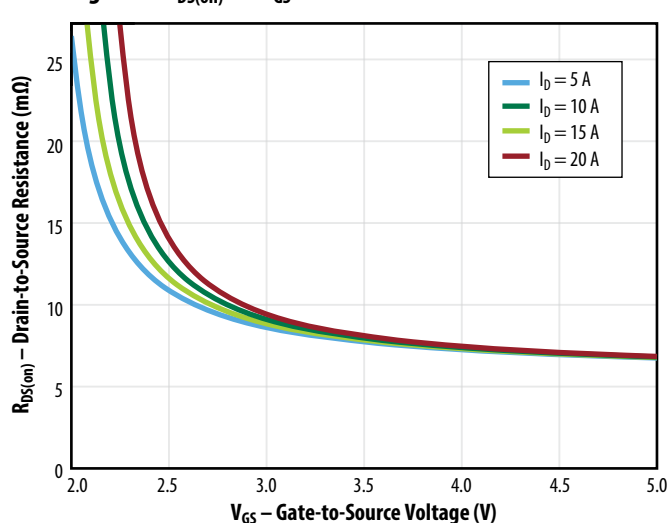
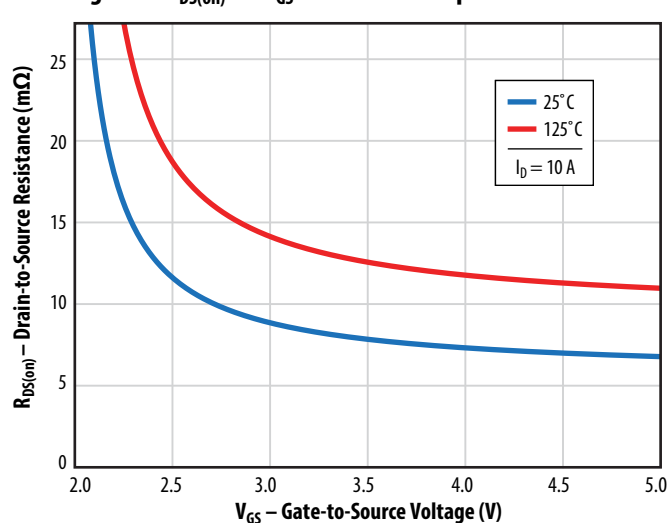
Figure 3: $R_{DS(on)}$ vs. V_{GS} for Various Drain CurrentsFigure 4: $R_{DS(on)}$ vs. V_{GS} for Various Temperatures

Figure 5a: Capacitance (Linear Scale)

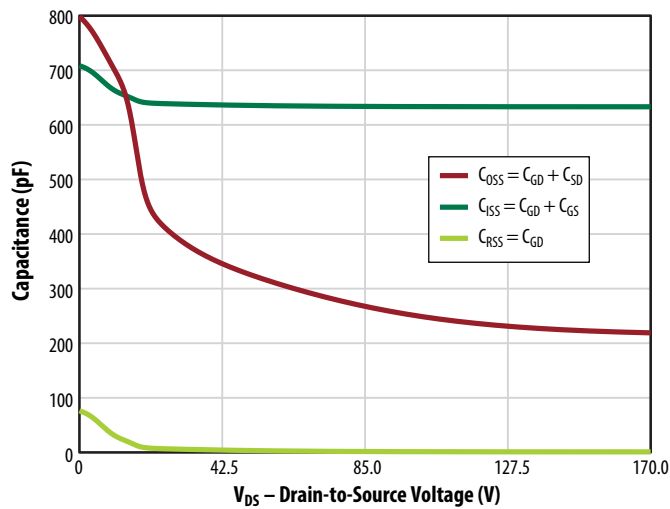


Figure 5b: Capacitance (Log Scale)

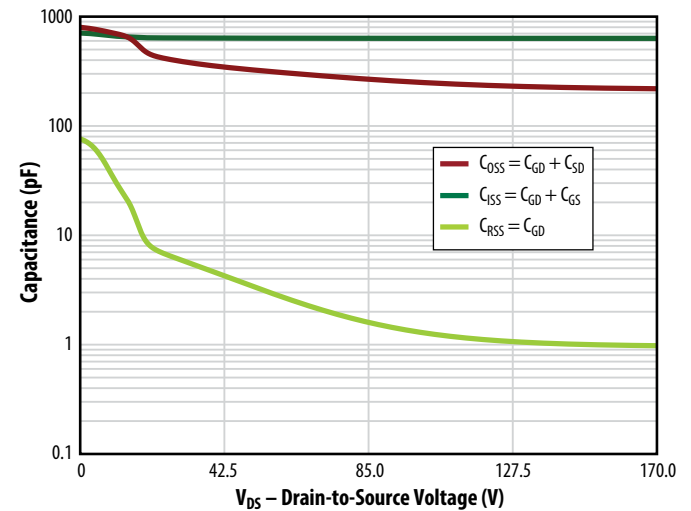
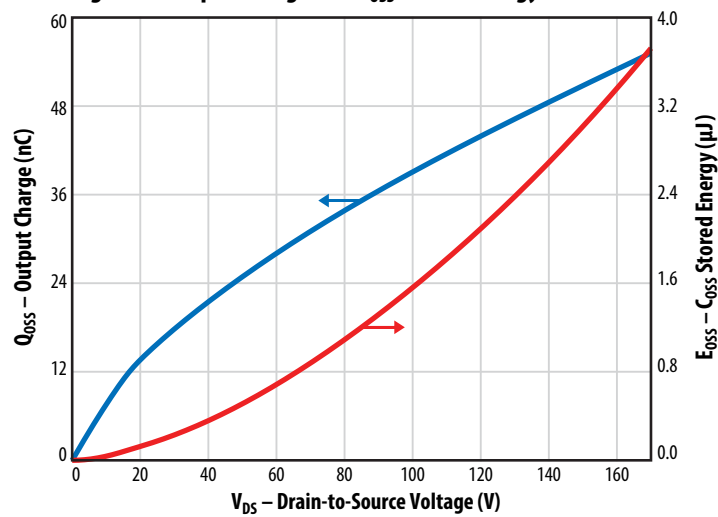
Figure 6: Output Charge and C_{OSS} Stored Energy

Figure 7: Gate Charge

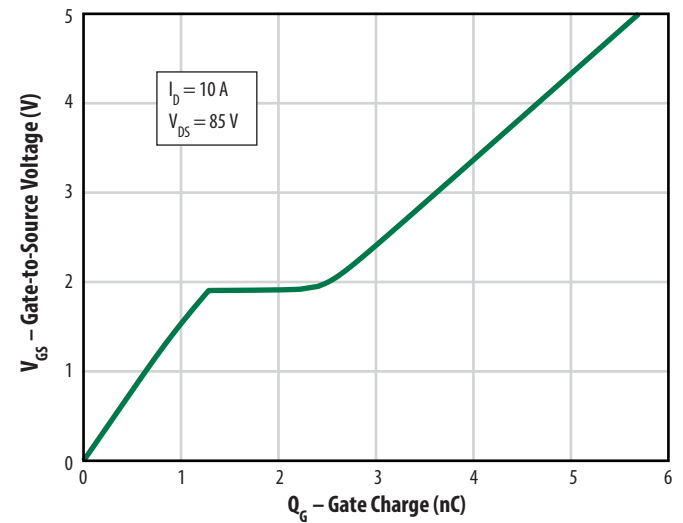


Figure 8: Reverse Drain-Source Characteristics

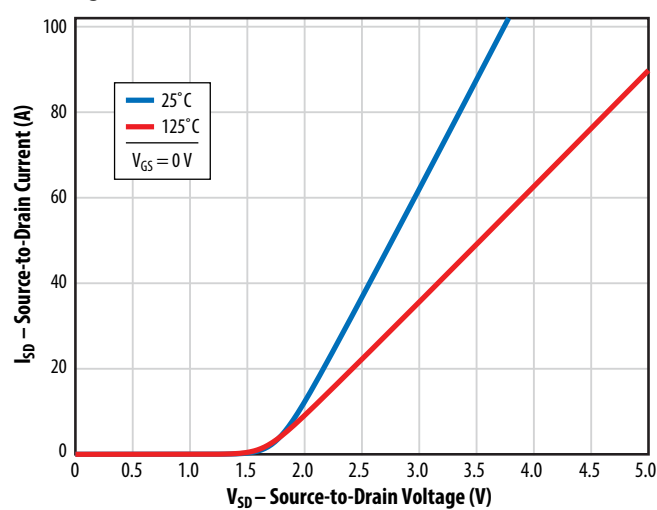


Figure 9: Normalized On-State Resistance vs. Temperature

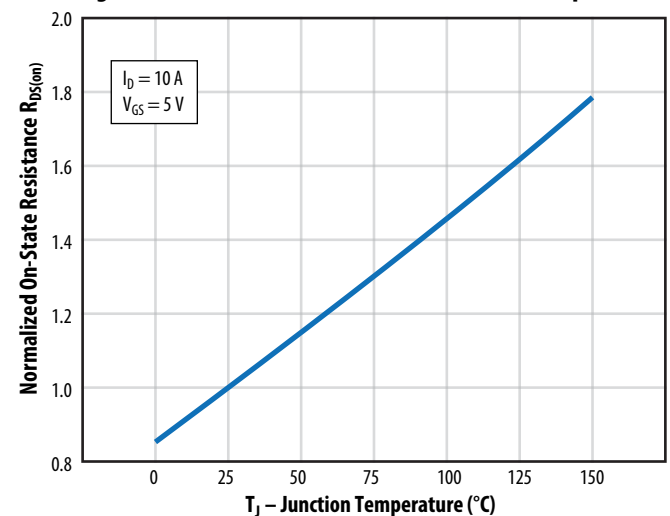


Figure 10: Normalized Threshold Voltage vs. Temperature

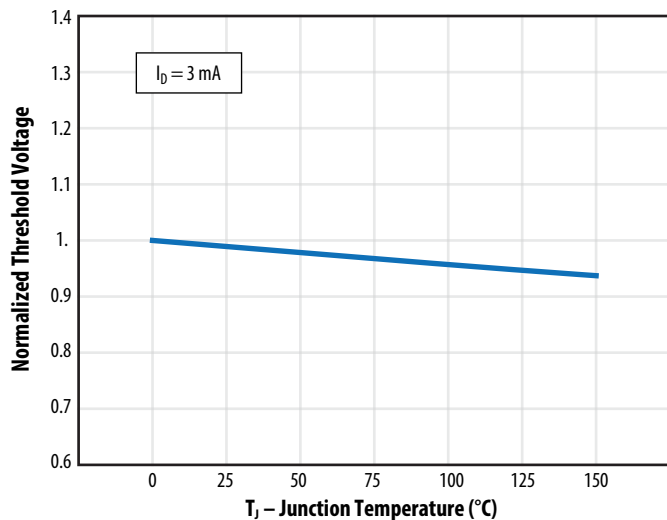


Figure 11: Safe Operating Area

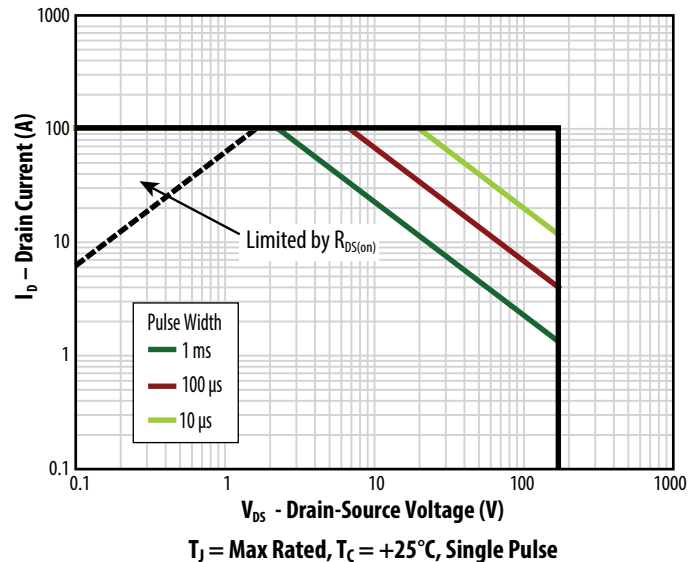
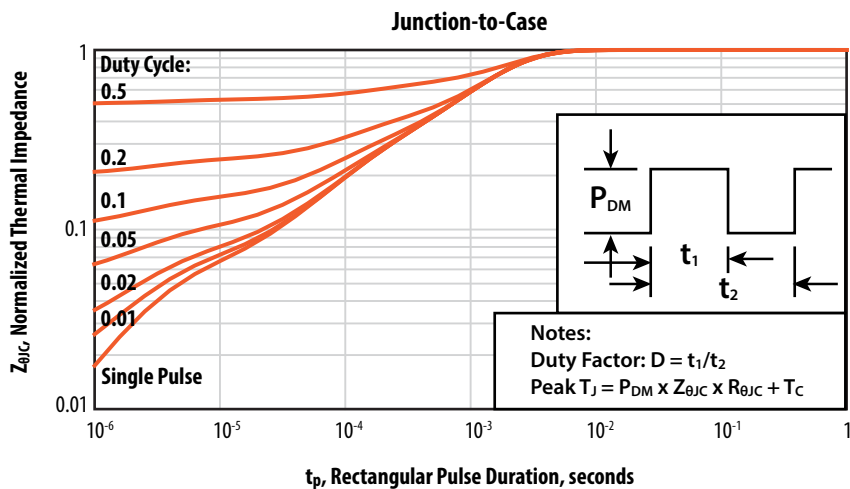
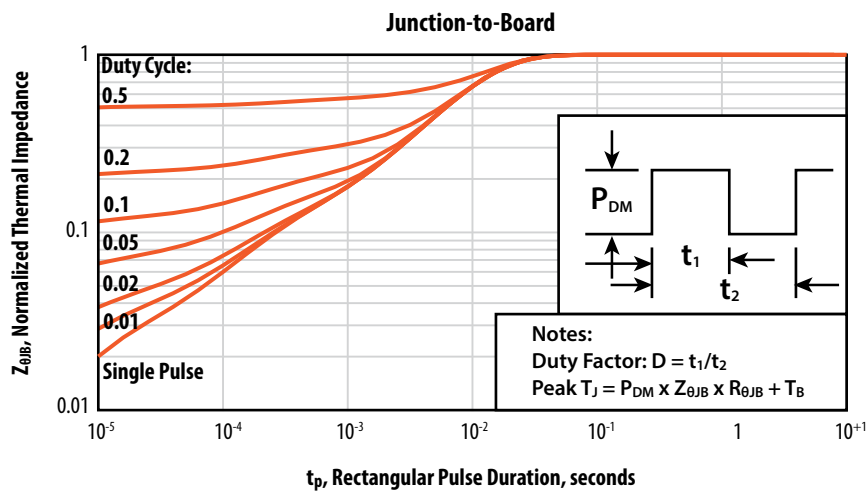


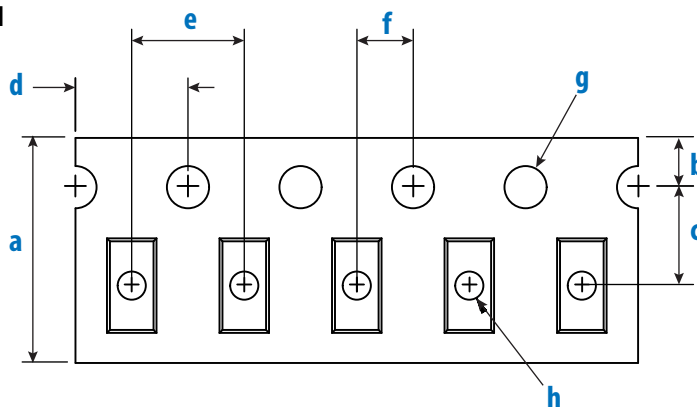
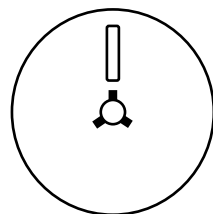
Figure 12: Transient Thermal Response Curves



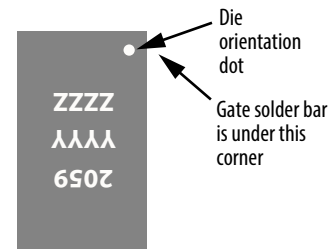
TAPE AND REEL CONFIGURATION

4 mm pitch, 8 mm wide tape on 7" reel

7" inch reel



Loaded Tape Feed Direction →



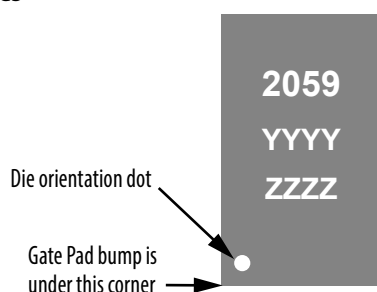
Die is placed into pocket solder bump side down (face side down)

EPC2059 (Note 1)	Dimension (mm)		
	Target	MIN	MAX
a	8.00	7.90	8.30
b	1.75	1.65	1.85
c (Note 2)	3.50	3.45	3.55
d	4.00	3.90	4.10
e	4.00	3.90	4.10
f (Note 2)	2.00	1.95	2.05
g	1.50	1.50	1.60
h	1.00	0.95	1.05

Note 1: MSL 1 (moisture sensitivity level 1) classified according to IPC/JEDEC industry standard.

Note 2: Pocket position is relative to the sprocket hole measured as true position of the pocket, not the pocket hole.

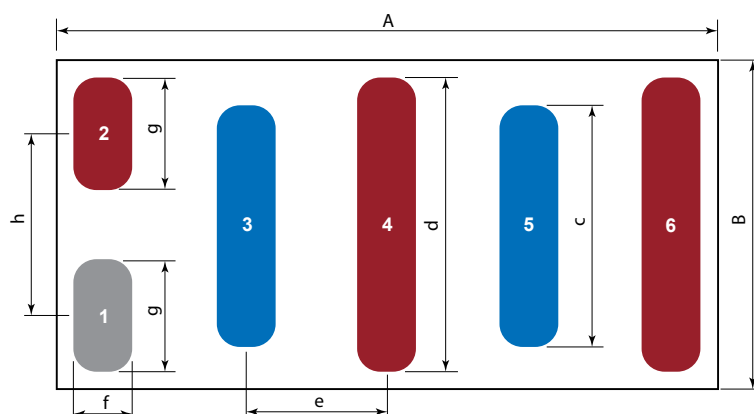
DIE MARKINGS



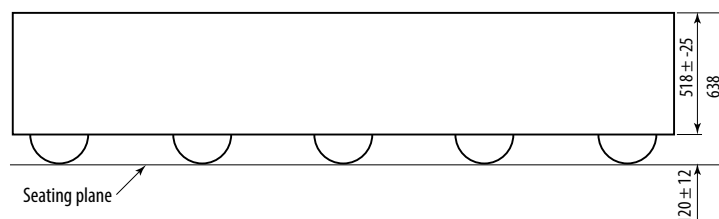
Part Number	Laser Markings		
	Part # Marking Line 1	Lot _Date Code Marking Line 2	Lot _Date Code Marking Line 3
EPC2059	2059	YYYY	ZZZZ

DIE OUTLINE

Solder Bump View



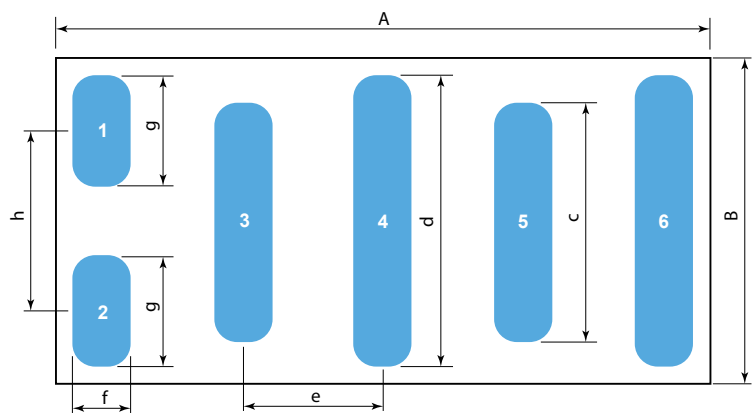
Side View



DIM	Micrometers		
	MIN	Nominal	MAX
A	2770	2800	2830
B	1370	1400	1430
c		1010	
d		1250	
e		600	
f		250	
g		475	
h		775	

Pad 1 is Gate;
 Pads 2, 4, 6 are Source;
 Pads 3, 5 are Drain

RECOMMENDED
LAND PATTERN
(units in μm)

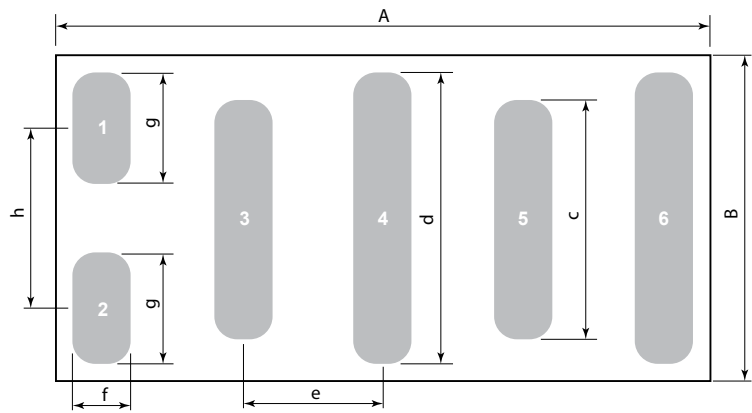


Land pattern is solder mask defined.
Solder mask is same as bump.
It is recommended to have on-Cu trace PCB vias,

Pad 1 is Gate;
Pads 2,4,6
are Source;
Pads 3,5 are Drain

DIM	Nominal
A	2800
B	1400
c	1010
d	1250
e	600
f	250
g	475
h	775

RECOMMENDED
STENCIL DRAWING
(units in μm)



DIM	Nominal
A	2800
B	1400
c	1010
d	1250
e	600
f	250
g	475
h	775

Recommended stencil should be 4 mil (100 μm) thick, must be laser cut, openings per drawing.
The corner has a radius of R60.
Intended for use with SAC305 Type 3 solder, reference 88.5% metals content.
Split stencil design can be provided upon request, but EPC has tested this stencil design and not found any scooping issues.
Additional assembly resources available at <https://epc-co.com/epc/DesignSupport/AssemblyBasics.aspx>

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